

# **Dual N-Channel 60-V (D-S) MOSFET**

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}$ ( $\Omega$ )	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)			
60	0.019 at V <sub>GS</sub> = 10 V	28	22 50			
00	0.022 at V <sub>GS</sub> = 4.5 V	20	23 nC			

DFN5X6

Top View

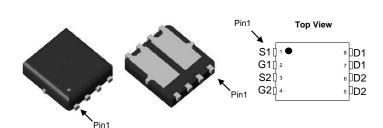
#### **FEATURES**

- DT-Trench Power MOSFET
- 100 %  $\rm R_{\rm g}$  and UIS Tested

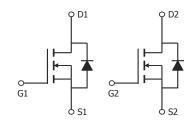


#### **APPLICATIONS**

- · Notebook System Power
- · Synchronous Buck Converter
- · Notebook Vcore



**Bottom View** 



N-Channel MOSFET N-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	60	V
Gate-Source Voltage		V <sub>GS</sub>	± 20	_ v
	T <sub>C</sub> = 25 °C		28 <sup>a</sup>	
Continuous Proin Current (T. = 150 °C)	T <sub>C</sub> = 70 °C	1 , —	22	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	16 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		9 <sup>b, c</sup>	_
Pulsed Drain Current	I <sub>DM</sub>	112	A	
0 " 0 0 0 0	T <sub>C</sub> = 25 °C		20	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	15 <sup>b, c</sup>	
Avalanche Current	1 = 0.1 ml l	I <sub>AS</sub>	22	
Single-Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	41	mJ
	T <sub>C</sub> = 25 °C		35	
Mayimum Dawar Dissination	T <sub>C</sub> = 70 °C		26	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	15 <sup>b, c</sup>	VV
	T <sub>A</sub> = 70 °C		10 <sup>b, c</sup>	
Operating Junction and Storage Temperature Rang	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	45	55	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	8	10	]	

#### Notes

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c = 10 s
- d. Maximum under Steady State conditions is 85 °C/W.

Parameter	Symbol Test Conditions		Min. Typ.		Max.	Unit
Static	<u> </u>		<u>'</u>	<u> </u>		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			55		m\//°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 6.3		mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		4	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zara Cata Valtaga Drain Current	1	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0 V			1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	μA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	28			Α
Dunin Course On Chata Basistanas	Reservi	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6A		0.019	0.025	Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 6A		0.022	0.030	Ω
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 6A		40		S
Dynamic <sup>b</sup>					<u>'</u>	
Input Capacitance	C <sub>iss</sub>			1950		
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V, f = 1 MHz		930		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			510		
Total Gate Charge	Qg			35		_
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$		6.3		nC
Gate-Drain Charge	Q <sub>gd</sub>			11		
Gate Resistance	$R_g$	f = 1 MHz		4.9	6.2	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			16	19	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 48 V, $R_{L}$ = 5.4 $\Omega$		35	66	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong 6 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		30	39	
Fall Time	t <sub>f</sub>			26	31	
Turn-On Delay Time	t <sub>d(on)</sub>			9	18	ns
Rise Time	t <sub>r</sub>	$V_{DD} = 48 \text{ V}, R_{L} = 5.4 \Omega$		15	15	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong 6A$ , $V_{GEN} = 10 \text{ V}$ , $R_g = 1 \Omega$		19	28	
Fall Time	t <sub>f</sub>			20	35	İ
<b>Drain-Source Body Diode Characterist</b>	ics					
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			28	_
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				112	Α
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 2 A		0.7	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			26	55	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			26	55	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 5.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 °\text{C}$		20		
Reverse Recovery Rise Time	t <sub>b</sub>			7		ns

### Notes:

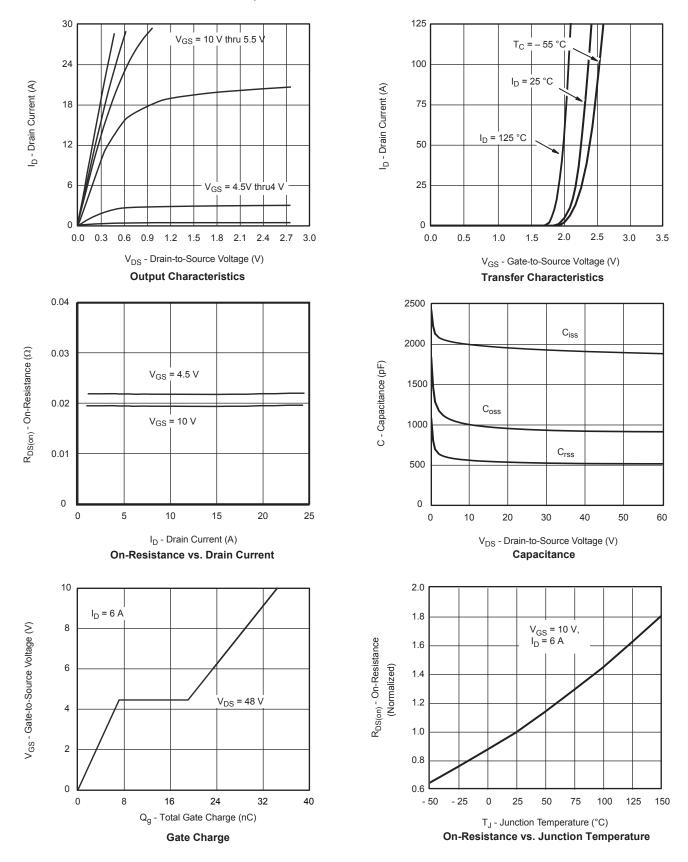
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

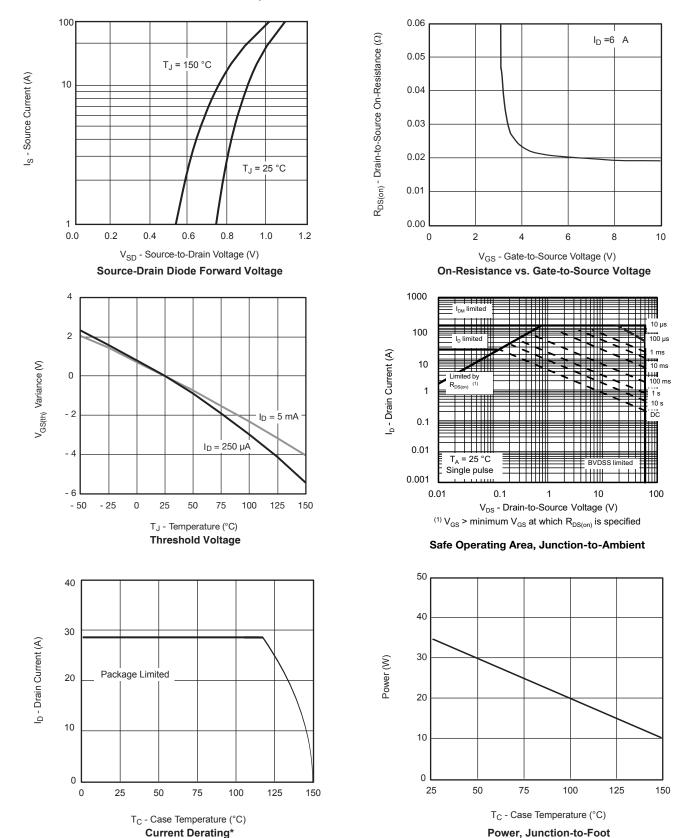
b. Guaranteed by design, not subject to production testing.



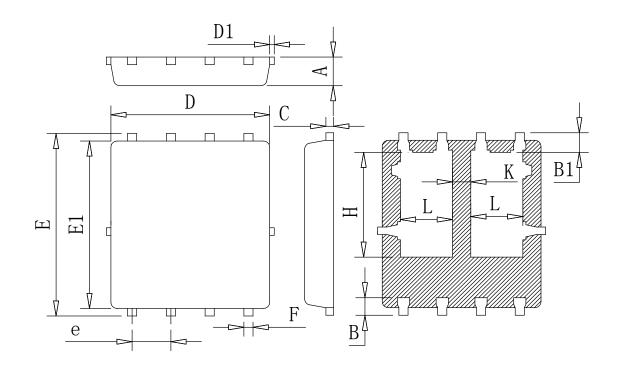
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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## **DFN5X6-8L-D PACKAGE OUTLINE**



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max
A	0.85	0.95	1.05
В	0.46	0.58	0.73
B1	0.52	0.65	0.78
С	0.18	0.254	0.32
D	4.70	5.20	5.50
D1	-	-	0.18
Е	5.75	6.05	6.35
E1	5.35	5.65	5.85
e	1.15	1.27	1.50
F	0.15	0.30	0.50
Н	3.15	3.47	3.80
L	1.35	1.70	2.10
K	0.35	0.60	1.00



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